



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN20260309000.1
Qualification of additional Assembly sites for select QFN package devices
Change Notification / Sample Request

Date: March 09, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260309000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS259823ONRGET	TPS259823ONRGET
TPS259802ONRGER	NULL
TPS259827LNRGET	TPS259827LNRGET
TPS259807ONRGER	NULL
TPS259824ONRGET	TPS259824ONRGET
TPS259824ONRGER	TPS259824ONRGER
TPS259804ONRGER	NULL
TPS259822LNRGER	595-TPS259822LNRGER
TPS259823ONRGER	NULL
TPS259827LNRGER	TPS259827LNRGER

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN#20260309000.1	PCN Date:	March 09, 2026
Title:	Qualification of additional Assembly sites for select QFN package devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	June 07, 2026	Sample requests accepted until:	May 08, 2026*

***Sample requests received after May 08, 2026 will not be supported.**

Change Type:

<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:

QFN Build sites	
Assembly Sites	CLARK, CDAT, UTL3, TIEMA, MLA, CARZ
Mount Compound	4207123
	4206201
	SID#435143
	SID#PZ0035
	SID#PZ0037
	SID#PZ0109
	4211470
	4207768
	4205846
Mold Compound	SID#443156
	4222198
	4208625
Lead frame Finish	NiPdAu, Matte Sn
MSL level	1, 2

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
CDAT	CDA	CHN	Chengdu
UTL3	UT3	THA	Bangpakong
TIEMA	CU6	MYS	Melaka
MLA	MLA	MYS	Kuala Lumpur
CARZ	CSZ	CHN	Jiangsu
CLARK	QAB	PHL	Angeles city, Pampanga

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 2Q

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TPS259802ONRGER	TPS259822LNRGET	TPS259823ONRGER	TPS259824ONRGET
TPS259803ONRGER	TPS259822ONRGER	TPS259823ONRGET	TPS259825ONRGER
TPS259804ONRGER	TPS259822ONRGET	TPS259824LNRGER	TPS259827LNRGER
TPS259807ONRGER	TPS259823LNRGER	TPS259824LNRGET	TPS259827LNRGET
TPS259822LNRGER	TPS259823LNRGET	TPS259824ONRGER	TPS259827ONRGET



TI Information
Selective Disclosure

VQFN Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	CDAT TPS26630RGE TCA9548ARGERQ1 BQ24232HRGTR	CLARK CSD95410RRB TPS259824ONRGER CC3220SM2ARGKR
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	
TC	Temperature Cycling -55/125C	1000 Cycles		3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
THB	Temperature Humidity Bias, 85C/85%RH	1000 hours	-	-
HTSL	High Temp. Storage Bake 150C	1000 hours	-	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHA	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	3/231/0

AC	Autoclave 121C	96 hours	-	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (BQ24232HRGTR)	3/66/0 (CC3220SM2ARGKR)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	CARZ TPS259827LNRGER TPS51123RGER TLV75733PDRV	TIEMA TPS259570DSGR TPS26630RGER BQ24735RGRR
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	-
THB	Temperature Humidity Bias, 85C/85%RH	1000 hours	-	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	-
AC	Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TPS51123RGER)	3/66/0 (BQ24735RGRR)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	MLA BQ9000RSM TRF7970ARHBR TPS650240RHBR	UTL3 THS4541QWRGTRQ1 TMUXHS4446RET INA210AIRSWR
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
THB	Temperature Humidity Bias, 85C/85%RH	1000 hours	-	-
HTSL	High Temp. Storage Bake 150C	1000 hours	-	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TPS650240RHBR)	3/66/0 (THS4541QWRGTRQ1)
MQ	Manufacturability	-	Pass	Pass

CSD9541ORRB, TPS259824ONRGER, CC3220SM2ARGKR, TCA9548ARGERQ1, TPS259827LNRGER, TPS51123RGER, TPS259570DSGR, BQ24735RGRR, TRF7970ARHBR, BQ9000RSM, TPS650240RHBR, THS4541QWRGTRQ1, TMUXHS4446RET are qualified at L2-260C MSL rating.

TPS26630RGE, INA210AIRSWR, TLV75733PDRV are qualified at L1-260C MSL rating

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable

- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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